CT DBLP31.12

FIREFLY®

The FIREFLY E2218 family expands OSRAM Opto Semiconductors' portfolio of visible products for use in mobile devices like fitness tracking or health monitoring. It offers the highest efficiency output and lowest forward Voltage (Vf) operation, for longer battery life in portable applications. The compact size of only 1.8 mm x 2.2 mm x 0.6 mm allows customers the benefit of more flexible product designs. The true green CT DBLP31.12 is specially designed for Heart Rate Monitor applications. It features a very high luminous intensity to ideally match these applications.



Applications

 Health Monitoring (Heart Rate Monitoring, Pulse Oximetry)

Features:

- Package: white SMT package
- Chip technology: UX:3
- Typ. Radiation: 120° (Lambertian emitter)
- Color: $\lambda_{dom} = 536$ nm (• true green)
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)





Ordering Information

| Туре | Luminous Intensity ¹⁾ I _F = 20 mA I _v | Ordering Code |
|---------------------------|--|---------------|
| CT DBLP31.12-6C5D-56-J6Q4 | 3150 5000 mcd | Q65112A4607 |
| CT DBLP31.12-6C5D-56-J6U6 | 3150 5000 mcd | Q65112A6091 |



Maximum Ratings

| Parameter | Symbol | | Values |
|---|------------------|------|--------|
| Operating Temperature | T _{op} | min. | -40 °C |
| | υp | max. | 85 °C |
| Storage Temperature | T _{stg} | min. | -40 °C |
| | Sig | max. | 85 °C |
| Junction Temperature | Tj | max. | 125 °C |
| Forward current | I _F | min. | 2.5 mA |
| T _s = 25 °C | · | max. | 140 mA |
| Surge Current t ≤ 10 μs; D = 0.005 ; T _s = 25 °C | Ι _{FS} | max. | 500 mA |
| ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B) | V_{ESD} | | 8 kV |
| Reverse current ²⁾ | I _R | max. | 200 mA |



Characteristics

 $I_{_{
m F}}$ = 20 mA; $T_{_{
m S}}$ = 25 °C

| Parameter | Symbol | | Values | |
|--|--------------------|------|----------|--|
| Peak Wavelength | λ_{peak} | typ. | 536 nm | |
| Dominant Wavelength ³⁾ | λ_{dom} | min. | 526 nm | |
| I _F = 20 mA | dom | typ. | 536 nm | |
| | | max. | 544 nm | |
| Viewing angle at 50% $\rm I_v$ | 2φ | typ. | 120 ° | |
| Forward Voltage 4) | V _F | min. | 2.00 V | |
| I _F = 20 mA | · | typ. | 2.30 V | |
| | | max. | 2.80 V | |
| Reverse voltage (ESD device) | V _{r esd} | min. | 45 V | |
| Reverse voltage 2) | V _R | max. | 1.2 V | |
| I _R = 20 mA | | | | |
| Real thermal resistance junction/solderpoint ⁵⁾ | $R_{thJS real}$ | typ. | 15 K / W | |
| | | max. | 18 K / W | |



Brightness Groups

| Group | Luminous Intensity ¹⁾ I _F = 20 mA min. I _v | Luminous Intensity. ¹⁾ I _F = 20 mA max. I _v | Luminous Flux ⁶⁾ I _F = 20 mA typ. Φ _v |
|-------|--|---|---|
| 6C | 3150 mcd | 3550 mcd | 10100 mlm |
| 7C | 3550 mcd | 4000 mcd | 11300 mlm |
| 8C | 4000 mcd | 4500 mcd | 12800 mlm |
| 5D | 4500 mcd | 5000 mcd | 14300 mlm |

Forward Voltage Groups

| Group Forward Voltage ⁴⁾ I _F = 20 mA min. V _F | | Forward Voltage ⁴⁾ I _F = 20 mA max. V _F | |
|---|--------|---|--|
| J6 | 2.00 V | 2.30 V | |
| Q4 | 2.30 V | 2.50 V | |
| U6 | 2.50 V | 2.80 V | |

Wavelength Groups

| Group Dominant Wavelength ³⁾ $I_F = 20 \text{ mA}$ min. | | Dominant Wavelength ³⁾ I _F = 20 mA max. |
|--|------------------|---|
| | λ _{dom} | λ _{dom} |
| 5 | 526 nm | 535 nm |
| 6 | 535 nm | 544 nm |



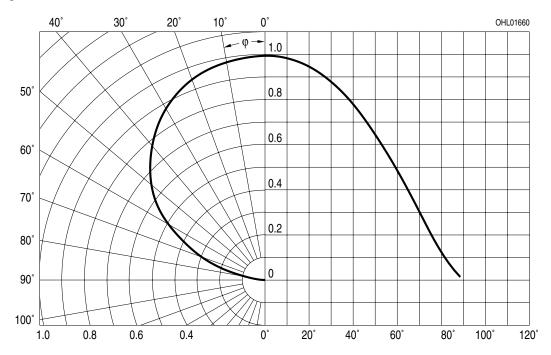
Group Name on Label

| Example: 5D-5-J6 Brightness | Wavelength | Forward Voltage |
|--------------------------------|------------|-----------------|
| 5D | 5 | J6 |



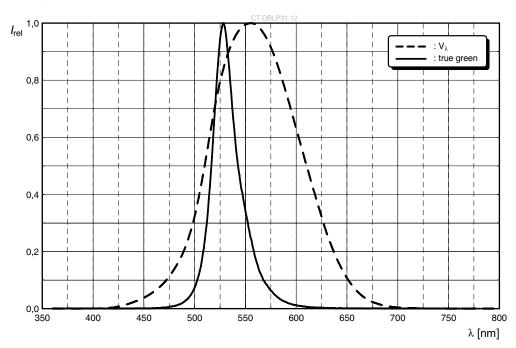
Radiation Characteristics ^{6), 7)}

 $I_{rel} = f(\phi); T_{s} = 25 \ ^{\circ}C$



Relative Spectral Emission⁶⁾

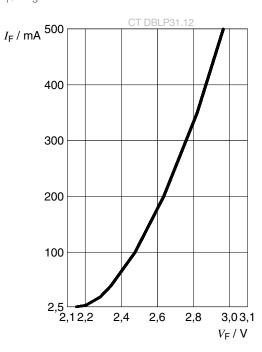
 $I_{rel} = f(\lambda); I_{F} = 20 \text{ mA}; T_{S} = 25 \text{ }^{\circ}\text{C}$





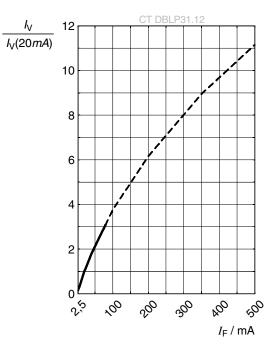
Forward current ^{6), 8)}

 $I_F = f(V_F); T_S = 25 \text{ °C}$



Relative Luminous Flux ^{6), 8)}

 $I_{v}/I_{v}(20 \text{ mA}) = f(I_{F}); T_{S} = 25 \text{ °C}$



Dominant Wavelength ⁶⁾

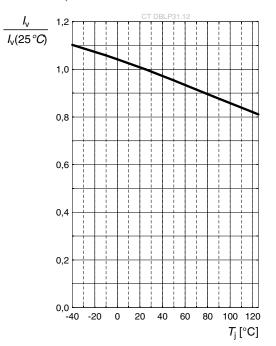
 $\Delta \lambda_{dom} = f(I_F); T_S = 25 \ ^{\circ}C$ 8 $\Delta\lambda_{\text{dom}}$ [nm] 6 4 2 0 -2 -4 -6 -8 -10 5 20 20 60 % ,00 20 , AO *I*_F [mA]



Forward Voltage ⁶) $\Delta V_F = V_F - V_F (25 \ ^{\circ}C) = f(T_j); I_F = 20 \text{ mA}$ $\Delta V_F [V] \stackrel{0,3}{0,2} \xrightarrow{CT DBLP31.12}$

Relative Luminous Intensity⁶⁾

 $I_{v}/I_{v}(25 \text{ °C}) = f(T_{i}); I_{F} = 20 \text{ mA}$



Dominant Wavelength⁶⁾

-0,2

-0,3 -40 -20

0 20

40 60 80

100 120

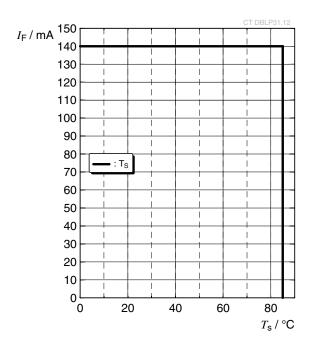
*T*_i [°C]

 $\Delta \lambda_{dom} = \lambda_{dom} - \lambda_{dom} (25 \ ^{\circ}C) = f(T_j); I_F = 20 \text{ mA}$ $\varDelta\lambda$ dom [nm] ¹⁰ 8 6 4 2 0 -2 -4 -6 -8 -40 -20 0 20 40 60 80 100 120 $T_j [^{\circ}C]$



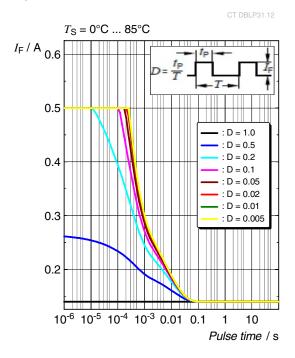


 $I_{F} = f(T)$



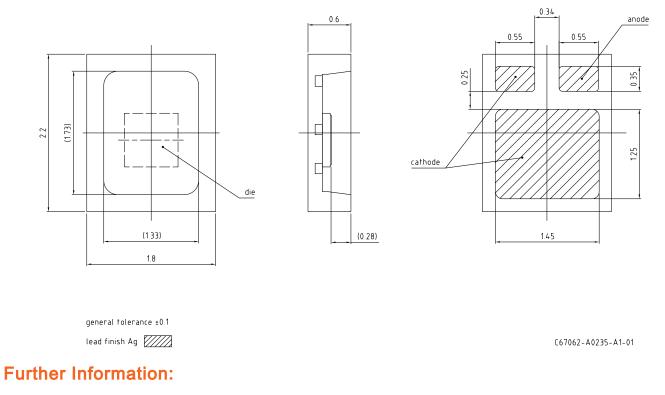
Permissible Pulse Handling Capability

 $I_{F} = f(t_{p}); D: Duty cycle$





Dimensional Drawing ⁹⁾



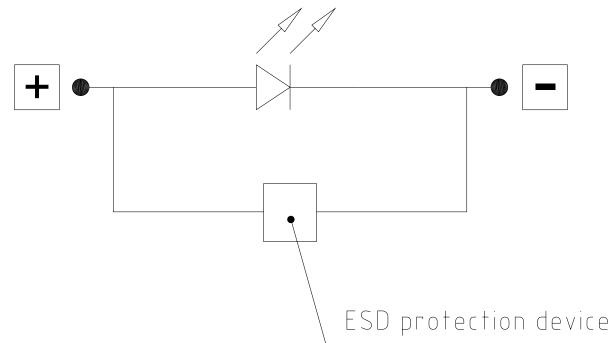
Approximate Weight: 6.0 mg

ESD advice:

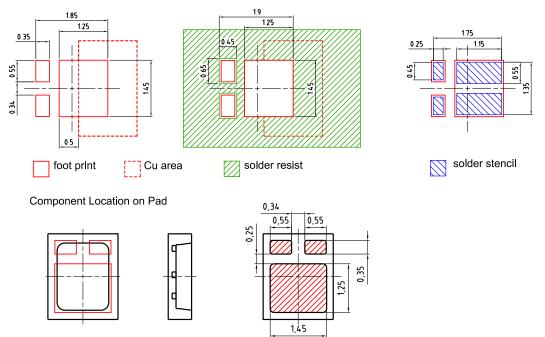
The device is protected by ESD device which is connected in parallel to the Chip.



Electrical Internal Circuit



Recommended Solder Pad⁹⁾



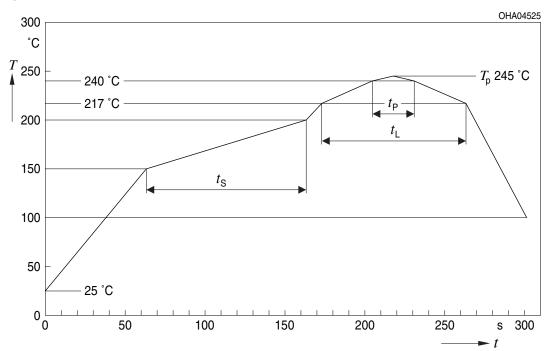
E062.3010.218 -01

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.



Reflow Soldering Profile

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E



| Profile Feature | Symbol | Pb-Free (SnAgCu) Assembly | | | Unit |
|--|----------------|---------------------------|----------------|---------|------|
| | | Minimum | Recommendation | Maximum | |
| Ramp-up rate to preheat ^{*)} 25 °C to 150 °C | | | 2 | 3 | K/s |
| Time t _s T _{smin} to T _{smax} | t _s | 60 | 100 | 120 | S |
| Ramp-up rate to peak ^{*)} T_{smax} to T_{p} | | | 2 | 3 | K/s |
| Liquidus temperature | TL | | 217 | | °C |
| Time above liquidus temperature | t | | 80 | 100 | S |
| Peak temperature | Τ _Ρ | | 245 | 260 | °C |
| Time within 5 °C of the specified peak temperature T_p - 5 K | t _P | 10 | 20 | 30 | S |
| Ramp-down rate* T _P to 100 °C | | | 3 | 6 | K/s |
| Time 25 °C to T _P | | | | 480 | S |

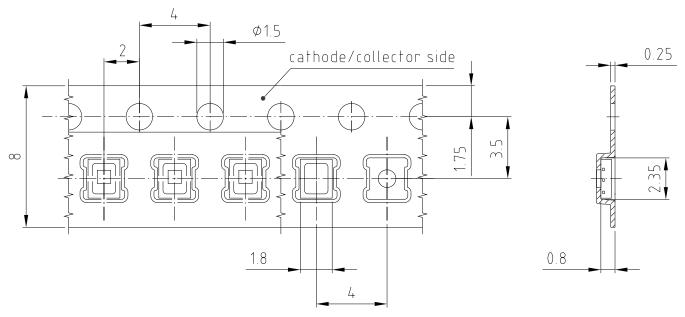
All temperatures refer to the center of the package, measured on the top of the component

* slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range



CT DBLP31.12

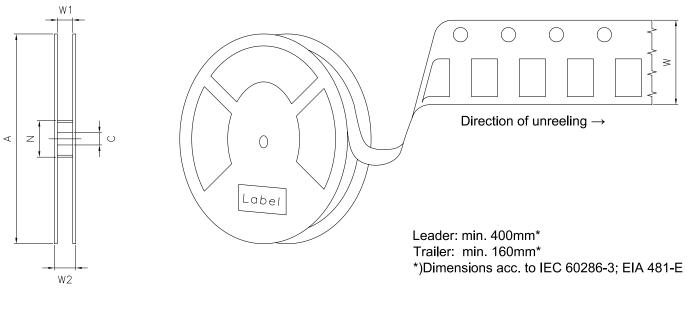




C67062-A0235-B6-01



Tape and Reel ¹⁰⁾

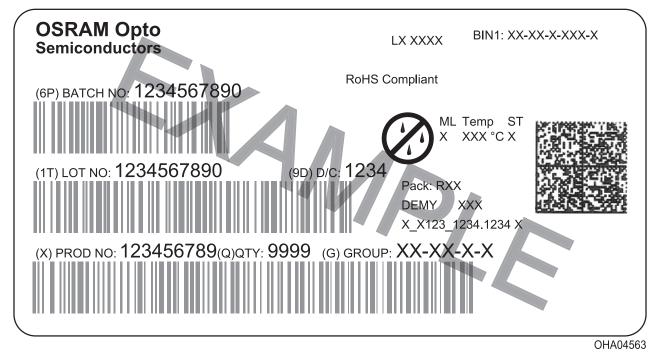


Reel Dimensions

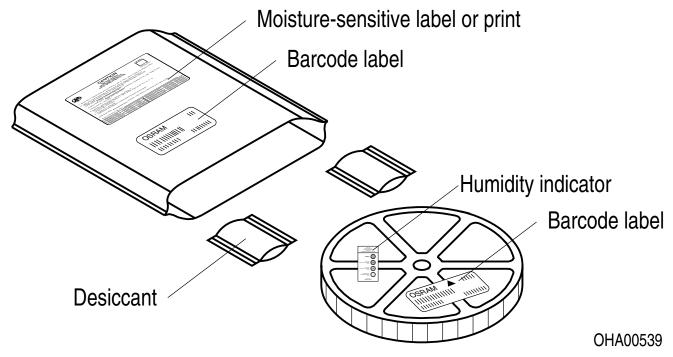
| А | W | N _{min} | W ₁ | $W_{2 \max}$ | Pieces per PU |
|--------|--------------------|------------------|----------------|--------------|---------------|
| 180 mm | 8 + 0.3 / - 0.1 mm | 60 mm | 8.4 + 2 mm | 14.4 mm | 4000 |



Barcode-Product-Label (BPL)



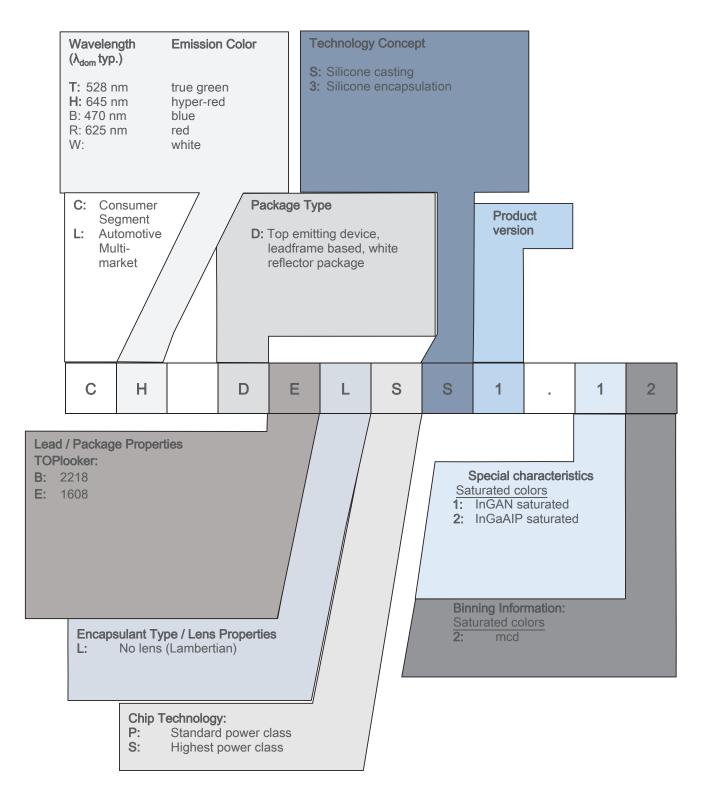
Dry Packing Process and Materials⁹⁾



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Type Designation System





Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **moderate risk (exposure time 0.25 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

OSRAM OS products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using OSRAM OS components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform the local sales partner of OSRAM OS immediately and OSRAM OS and buyer and /or customer will analyze and coordinate the customer-specific request between OSRAM OS and buyer and/or customer.



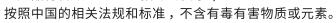
Glossary

- ¹⁾ **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 8 % and an expanded uncertainty of ± 11 % (acc. to GUM with a coverage factor of k = 3).
- ²⁾ **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- ³⁾ **Wavelength:** The wavelength is measured at a current pulse of typically 25 ms, with an internal reproducibility of ±0.5 nm and an expanded uncertainty of ±1 nm (acc. to GUM with a coverage factor of k = 3).
- ⁴⁾ **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of ± 0.05 V and an expanded uncertainty of ± 0.1 V (acc. to GUM with a coverage factor of k = 3).
- ⁵⁾ **Thermal Resistance:** Rth max is based on statistic values (6σ).
- ⁶⁾ **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁷⁾ **Testing temperature:** TA = 25°C (unless otherwise specified)
- ⁸⁾ **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- ⁹⁾ **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ¹⁰⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



| Revision History | | | |
|------------------|------------|--|--|
| Version | Date | Change | |
| 1.2 | 2019-09-17 | Derating (Diagrams) Maximum Ratings | |
| 1.3 | 2021-03-29 | Electro - Optical Characteristics (Diagrams) | |







e